

Appl. No. 10/812,464
Amdt. dated May 3, 2005
Reply to Notice of April 26, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

Claim 1 (currently amended): An apparatus, comprising:

an adhesion layer abutting a conductive pad;

a molybdenum-containing barrier layer abutting said adhesion layer;

a wetting layer abutting said molybdenum-containing barrier layer; and

high tin content solder material abutting said wetting layer, said high tin content solder material having a least about 75% tin by weight.

Claim 2 (original): The apparatus of claim 1, wherein said molybdenum-containing barrier layer comprises a material containing at least about 90% (atomic) molybdenum.

Claim 3 (original): The apparatus of claim 1, wherein said high tin content solder material comprises a material containing at least about 90% (by weight) tin.

Claim 4 (original): The apparatus of claim 1, further comprising said conductive pad abutting at least one layer of low k dielectric material.

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Claim 5 (original): The apparatus of claim 4, wherein said at least one layer of low-k dielectric material comprises at least one layer of carbon doped oxide.

Claim 6 (original): The apparatus of claim 1, wherein said wetting layer is substantially subsumed in said high tin content solder material forming an intermetallic compound layer.

Claims 7-20 (canceled).